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EXAMINER	
MATTHEWS, COLLEEN ANN	
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2811	

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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No.	Applicant(s)	
	09/876,396	KARIYAZAKI, SYUUICHI	
	Examiner	Art Unit	
	Colleen A. Matthews	2811	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE *3* MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1)☐ Responsive to communication(s) filed on *09 February 2009*.

2a)☒ This action is **FINAL**. 2b)☐ This action is non-final.

3)☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4)☒ Claim(s) *1-11* is/are pending in the application.

4a) Of the above claim(s) _____ is/are withdrawn from consideration.

5)☐ Claim(s) _____ is/are allowed.

6)☒ Claim(s) *1-11* is/are rejected.

7)☐ Claim(s) _____ is/are objected to.

8)☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9)☐ The specification is objected to by the Examiner.

10)☐ The drawing(s) filed on _____ is/are: a)☐ accepted or b)☐ objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11)☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12)☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a)☒ All b)☐ Some * c)☐ None of:

1.☒ Certified copies of the priority documents have been received.

2.☐ Certified copies of the priority documents have been received in Application No. _____.

3.☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) ☐ Notice of References Cited (PTO-892)
2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
3) ☐ Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date. _____.
4) ☐ Interview Summary (PTO-413) Paper No(s)/Mail Date. _____.
5) ☐ Notice of Informal Patent Application
6) ☐ Other: _____.

DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

> A person shall be entitled to a patent unless –
>
> (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1-2 and 4-11 are rejected under 35 U.S.C. 102(e) as being anticipated by U.S. Pat. No. 6,111,756 to Moresco.

Regarding claim 1, Moresco discloses a semiconductor device comprising:

a semiconductor member (Fig 1-2 & 33, element 5) having thereon a plurality of electrode terminals (see Fig 33); and

a mounting member (Fig 1-2, Fig 8, element 20) having a plurality of interconnect pads (within 22; see Figs 2 and 14) electrically and mechanically connected to the respective electrode terminals for mounting the semiconductor member on the mounting member; and

the interconnect pads forming a plurality of I/O cells including signal terminals, a portion of the I/O cells forming a first group (see Fig 14- first group considered as the white squares corresponding to ground pads) of I/O cells and another portion of the I/O cells forming a second group (see Fig 14- first group considered as the black squares corresponding to power pads) of I/O cells on an inner position of the mounting member

with respect to the first group of I/O cells, the first group of I/O cells including a plurality of rows of interconnect pads (see Fig 14, for example) disposed to encircle a center of the mounting member, and the second group of I/O cells including a plurality of rows of interconnect pads (see Fig 14 for example) disposed to encircle a center of the mounting member (also col 11 lies 48—col 12 line 40), the first and second groups of I/O cells being disposed directly under the semiconductor member (see Fig 2).

Regarding claim 2, Moresco discloses a semiconductor device, wherein the semiconductor member is a semiconductor chip (IC chip 5), the electrode terminals are internal electrodes disposed on a bottom surface of the semiconductor chip (shown in Figure 33), and the mounting member is a package substrate used for packaging thereon the semiconductor chip (col 21 lines 21-35).

Regarding claim 4, Moresco discloses a semiconductor device, where the I/O cells only include the signals terminals or terminals for power and ground intermingled among one another (col 5 lines 12-14 ad col 11 lies 43-45).

Regarding claim 5, Moresco discloses a semiconductor device, wherein the I/O cells include peripherals (Fig 1 element 60).

Regarding claim 6, Moresco discloses a semiconductor device, herein an interconnect line (Fig 8, element 42) is electrically connected to each of the interconnect pads and the interconnect lines electrically connected to the interconnect pads of at least one of the I/O cells are formed in a single interconnect layer.

Regarding claim 7, Moresco discloses a semiconductor device, wherein the interconnect pads and the interconnect lines electrically connected to the interconnect

pads in the single interconnect layer are formed on the surface of a packaging substrate (see Fig 9).

Regarding claim 8, Moresco discloses a semiconductor device, wherein the interconnect lines connected to the I/O cells located on inner positions extend between the I/O cells located on an outer periphery.

Regarding claim 9, Moresco discloses a semiconductor device, wherein the interconnect pads and the interconnect lines electrically connected to the interconnect pads are formed as a multi-layered interconnect layer in the substrate (see Fig 9).

Regarding claim 10, Moresco discloses a semiconductor device, wherein at least one of the first group (see Fig 14- first group considered as the white squares corresponding to ground pads) and the second group (see Fig 14- first group considered as the black squares corresponding to power pads) includes an outer group (see Fig 14- first group considered as the white squares corresponding to ground pads) and inner group (see Fig 14- first group considered as the black squares corresponding to power pads) disposed on the inner position of the mounting member with respect to the outer group (see Fig. 14, the center black square/power pad is disposed in an inner group).

Regarding claim 11, Moresco discloses a semiconductor device, wherein the interconnect lines electrically connected to the interconnect pads corresponding to the first group of I/O cells and interconnect lines electrically connected to the interconnect pads corresponding to the second group of I/0 cells are formed in different interconnect layers (see Fig 9).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

> (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claim 3 is rejected under 35 U.S.C. 103(a) as being unpatentable over U.S. Pat. No. 6,111,756 to Moresco as applied to claim 1 above, and further in view of Applicant's Admitted Prior Art of Figure 1 (AAPA).

Regarding claim 3, Moresco discloses a semiconductor device (IC chip 5), wherein the mounting member (chip carrier) is a semiconductor package for mounting the semiconductor chip member on a mounting substrate (see col 2 lines 20-32). Moreseco fails to explicitly disclose the semiconductor package including ball electrodes disposed on a bottom surface of a packaging substrate, and the mounting substrate forms a specified circuit by mounting the semiconductor package thereon.

AAPA discloses a semiconductor device (103) with the semiconductor package including ball electrodes (124) disposed on a bottom surface of a packaging substrate (102), and the mounting substrate (104) forms a specified circuit by mounting the semiconductor package thereon. It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Morseco to include the ball electrodes and configuration of the packaging as in AAPA in order to provide a device capable of connection with other devices in a system.

Response to Arguments

Applicant's arguments filed 02/09/2009 have been fully considered but they are not persuasive.

Applicant argues (page 6-7) that Moresco's pad array 24 is not disposed directly under the semiconductor member (IC chip 5). This argument is moot in view of the new interpretation of Moresco's array 22 as presented above.

Applicant argues (page 7-8) that Moresco is test equipment used to attached chips with high speed signal lines thus combining Morseco with AAPA would render Morsesco inoperable. In response the Examiner notes that Moresco's disclosure is directed towards providing a semiconductor member (IC chip) on a mounting member (carrier chip) (see col 2 lines 20-32) for the packaging of the device. Moresco does disclose that the semiconductor and mounting member may be tested, however, Moresco's mounting member is part of the semiconductor package final product and therefore the testing does not compromise the face that Moresco discloses the semiconductor member and mounting member. Further, the ball electrode features from AAPA would not render Moresco inoperable, it would allow for further connection of the chip carrier to other devices in a multichip module.

Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Colleen A. Matthews whose telephone number is (571)272-1667. The examiner can normally be reached on Monday - Friday 8AM-4:30PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Lynne Gurley can be reached on 571-272-1670. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/C. A. M./
Examiner, Art Unit 2811

/Lynne A. Gurley/
Supervisory Patent Examiner, Art Unit 2811